

1.8V PHASE LOCKED LOOP DIFFERENTIAL 1:10 SDRAM CLOCK DRIVER

FEATURES:

- · 1 to 10 differential clock distribution
- Optimized for clock distribution in DDR2 (Double Data Rate) SDRAM applications
- Operating frequency: 125MHz to 340MHz
- Very low skew: ≤40ps
- Very low jitter: ≤40ps
- 1.8V AVDD and 1.8V VDDQ
- CMOS control signal input
- Test mode enables buffers while disabling PLL
- Low current power-down mode
- Tolerant of Spread Spectrum input clock
- Available in 52-Ball VFBGA and 40-pin VFQFPN packages

APPLICATIONS:

Meets or exceeds JEDEC standard 82.8 for registered DDR2 clock driver

FUNCTIONAL BLOCK DIAGRAM

Along with SSTU32864/65/66, DDR2 register, provides complete solution for DDR2 DIMMs

DESCRIPTION:

The CSPU877A is a PLL based clock driver that acts as a zero delay buffer to distribute one differential clock input pair(CLK, CLK) to 10 differential output pairs $(Y_{[0:9]}, Y_{[0:9]})$ and one differential pair of feedback clock output (FBOUT, FBOUT). External feedback pins (FBIN, FBIN) for synchronization of the outputs to the input reference is provided. OE, OS, and Avod control the power-down and test mode logic. When Avod is grounded, the PLL is turned off and bypassed for test mode purposes. When the differential clock inputs (CLK, CLK) are both at logic low, this device will enter a low power-down mode. In this mode, the receivers are disabled, the PLL is turned off, and the output clock drivers are disabled, resulting in a current consumption device of less than 500µA.

The CSPU877A requires no external components and has been optimised for very low phase error, skew, and jitter, while maintaining frequency and duty cycle over the operating voltage and temperature range. The CSPU877A, designed for use in both module assemblies and system motherboard based solutions, provides an optimum high-performance clock source.

The CSPU877A is available in Commercial Temperature Range (0°C to +70°C). See Ordering Information for details.

LD or OE POWER OE DOWN AND LD, OS, or OE Y0 os TEST MODE Y0 PLL BYPASS AVDD LOGIC Y1 LD T1 Y2 ۲2 Y3 ۲3 Y4 ¥4 CLK Y5 CLK ¥5 10ΚΩ - 100ΚΩ Y6 PLL $\overline{Y}6$ FBIN Y7 FBIN T7 Y8 ¥8 Y9 ¥9 FBOUT FBOUT

NOTE

The Logic Detect (LD) powers down the device when a logic LOW is applied to both CLK and CLK.

The IDT logo is a registered trademark of Integrated Device Technology, Inc. COMMERCIAL TEMPERATURE RANGE

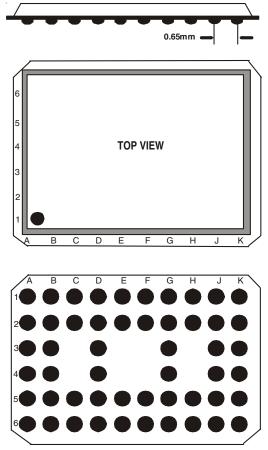
OCTOBER 2006

PIN CONFIGURATION

6	Y6	Y6	¥7	Y7	FBIN	FBIN	FBOUT	FBOUT	Y8	Y8
5	Y5	GND	GND	OS	Vddq	OE	Vddq	GND	GND	Y9
4	¥5	GND	NB	Vddq	NB	NB	Vddq	NB	GND	Y9
3	Yo	GND	NB	Vddq	NB	NB	Vddq	NB	GND	Y 4
2	Y0	GND	GND	Vddq	Vddq	VDDQ	VDDQ	GND	GND	¥4
1	Y1	T1	Y2	Y2	CLK	CLK	AGND	AVDD	Y3	¥3
	A	В	С	D	E	F	G	Н	J	ĸ

VFBGA TOP VIEW

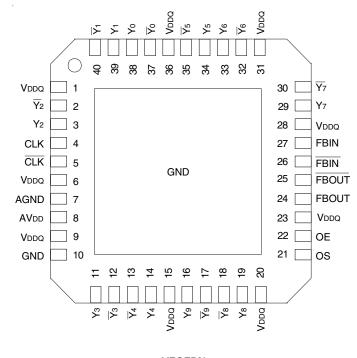
52 BALL VFBGA PACKAGE LAYOUT



IDTCSPU877A 1.8V PLL DIFFERENTIAL 1:10 SDRAM CLOCK DRIVER

COMMERCIALTEMPERATURERANGE

PIN CONFIGURATION, CONT.



VFQFPN TOP VIEW

ABSOLUTE MAXIMUM RATINGS^(1,2)

Symbol	Rating	Мах	Unit
Vddq, AVdd	Supply Voltage Range	-0.5 to +2.5	V
VI ⁽³⁾	Input Voltage Range	-0.5 to VDDQ + 0.5	V
Vo ⁽³⁾	Voltage range applied to any	-0.5 to VDDQ + 0.5	V
	output in the high or low state		
Ік	Input clamp current	±50	mA
(VI <0)			
Іок	Output Clamp Current	±50	mA
(Vo <0 or			
Vo > Vdda)			
lo	Continuous Output Current	±50	mA
(Vo =0 to VDDQ)			
VDDQ or GND	Continuous Current	±100	mA
TSTG	Storage Temperature Range	– 65 to +150	°C

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.
- 3. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed. This value is limited to 2.5V max.

CAPACITANCE⁽¹⁾

Parameter	Description	Min.	Тур.	Max.	Unit
Cin	Input Capacitance	2	_	3	рF
	VI = VDDQ or GND				
CιΔ	Delta Input Capacitance			0.25	рF
	CLK, CLK , FBIN, FBIN				
CL	Load Capacitance	_	10	_	pF

NOTE:

1. Unused inputs must be held high or low to prevent them from floating.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min.	Тур.	Max.	Unit
AVDD ⁽¹⁾	Supply Voltage		VDDQ		V
Vddq	I/O Supply Voltage	1.7	1.8	1.9	V
TA	Operating Free-Air Temperature	0	—	+70	°C

NOTE:

1. The PLL is turned off and bypassed for test purposes when AVDD is grounded. During this test mode, VDDD remains within the recommended operating conditions and no timing parameters are guaranteed.

PIN DESCRIPTION (VFBGA)

Pin Name	Pin Number	Description
AGND	G1	Ground for 1.8V analog supply
AVdd	H1	1.8V analog supply
CLK, CLK	E1, F1	Differential clock input with a 10K Ω to 100K Ω pulldown resistor
FBIN, FBIN	E6, F6	Feedback differential clock input
FBOUT, FBOUT	G6, H6	Feedback differential clock output
GND	B2 - B5, C2, C5, H2, H5, J2 - J5	Ground
VDDQ	D2 - D4, E2, E5, F2, G2 - G5	1.8V supply
OE	F5	Output Enable
OS	D5	Output Select (tied to GND or VDDO)
<u>Y[0:9]</u>	A3, A4, B1, B6, C1, C6, K1, K2, K5, K6	Buffered output of input clock, CLK
Y[0:9]	A1, A2, A5, A6, D1, D6, J1, J6, K3, K4	Buffered output of input clock, CLK
NB		No Ball

PIN DESCRIPTION (VFQFPN)

Pin Name	Pin Number	Description
AGND	7	Ground for 1.8V analog supply
AVdd	8	1.8V analog supply
CLK, CLK	4, 5	Differential clock input with a 10K Ω to 100K Ω pulldown resistor
FBIN, FBIN	26,27	Feedback differential clock input
FBOUT, FBOUT	24, 25	Feedback differential clock output
GND	10	Ground
VDDQ	1, 6, 9, 15, 20, 23, 28, 31, 36	1.8V supply
OE	22	Output Enable
OS	21	Output Select (tied to GND or VDDO)
Y[0:9]	3, 11, 14, 16, 19, 29, 33, 34, 38, 39	Buffered output of input clock, CLK
Y[0:9]	2, 12, 13, 17, 18, 30, 32, 35, 37, 40	Buffered output of input clock, CLK
NB		No Ball

FUNCTION TABLE^(1,2)

INPUTS						OUTPUTS			
AVdd	OE	OS	CLK	CLK	Y	Ŧ	FBOUT	FBOUT	PLL
GND	Н	Х	L	Н	L	Н	L	Н	OFF
GND	Н	Х	Н	L	Н	L	Н	L	OFF
GND	L	Н	L	Н	L(z)	L(z)	L	Н	OFF
					L(z)	L(z)			
GND	L	L	Н	L	Y7	<u>Y</u> 7	н	L	OFF
					Active	Active			
1.8V (nom)	L	Н	L	Н	L(z)	L(z)	L	Н	ON
					L(z)	L(z)			
1.8V (nom)	L	L	Н	L	Y7	<u>Y</u> 7	н	L	ON
					Active	Active			
1.8V (nom)	Н	Х	L	Н	L	Н	L	Н	ON
1.8V (nom)	Н	Х	Н	L	Н	L	Н	L	ON
1.8V (nom)	Х	Х	L ⁽³⁾	L ⁽³⁾	L(z)	L(z)	L(z)	L(z)	OFF
Х	Х	Х	Н	Н	Reserved				

NOTES:

1. H = HIGH Voltage Level

L = LOW Voltage Level

X = Don't Care

2. L(z) means the outputs are disabled to a LOW state, meeting the lobL limit in DC Electrical Characteristics table.

3. The device will enter a low power-down mode when CLK and CLK are both at logic LOW.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Commercial: $TA = 0^{\circ}C to + 70^{\circ}C$

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Vik	Input Clamp Voltage (All Inputs)	VDDQ = 1.7V, II = -18mA	—	_	- 1.2	V
VIL ⁽²⁾	Input LOW Voltage (OE, OS, CLK, CLK)		—	—	0.35Vddq	V
VIH ⁽²⁾	Input HIGH Voltage (OE, OS, CLK, CLK)		0.65Vddq	—	—	
VIN ⁽¹⁾	Input Signal Voltage		-0.3	—	VDDQ + 0.3	V
VID(DC) ⁽²⁾	DC Input Differential Voltage		0.3		VDDQ+0.4	V
Vod(3)	Output Differential Voltage	Avdd/Vddq = 1.7V	0.5	—	—	V
Vон	Output HIGH Voltage	IOH = -100µA, VDDQ = 1.7V to 1.9V	Vddq - 0.2			V
		IOH = -9mA, VDDQ = 1.7V	1.1		—	
Vol	Output LOW Voltage	IOL = 100µA, VDDQ = 1.7V to 1.9V			0.1	V
		IOL = 9mA, VDDQ = 1.7V			0.6	
IODL	Output Disabled LOW Current	OE = L, VODL = 100mV, AVDD/VDDQ = 1.7V	100		—	μA
lin	InputCurrent CLK, CLK	AVDD/VDDQ = Max., VI = 0V to VDDQ			±250	μA
	OE, OS, FBIN, FBIN	7			±10	
Iddld	Static Supply Current (IDDQ and IADD)	AVDD/VDDQ = Max., CLK and \overline{CLK} = GND			500	μA
Idd	Dynamic Power Supply Current (IDDQ and IADD) ^(4,5)	Avdd/Vddq = Max., CLK = 270MHz			300	mA

NOTES:

1. VIN specifies the allowable DC excursion of each different output.

2. VID is the magnitude of the difference between the input level on CLK and the input level on CLK. The CLK and CLK VIH and VIL limits are used to define the DC LOW and HIGH levels for the power down mode.

3. Vod is the magnitude of the difference between the true output level and the complementary level.

4. All Outputs are left open (unconnected to PCB).

5. Total Ibb = Ibb0 + Iabb = Fck * CPb * Vbb0, for Cpd = (Ibb0 + Iabb) / (Fck * Vbb0) where Fck is the input frequency, Vbb0 is the power supply, and CPb is the Power Dissipation Capacitance.

5

TIMING REQUIREMENTS

Symbol	Parameter	Min.	Max.	Unit
fclk	Operating Clock Frequency ^(1,2,3)	125	340	MHz
	Application Clock Frequency ^(2,4)	160	340	MHz
tDC	Input Clock Duty Cycle	40	60	%
t.	Stabilization Time ⁽⁵⁾		15	μs

NOTES:

1. 270MHz max clock frequency for parts assembled and tested prior to WW37.

2. The PLL will track a spread spectrum clock input.

3. Operating clock frequency is the range over which the PLL will lock, but may not meet all timing specifications. To be used only for low speed system debug.

4. Application clock frequency is the range over which timing specifications apply.

5. Stabilization time is the time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal after power up. During normal operation, the stabilization time is also the time required for the PLL circuit to obtain phase lock of its feedback signal to its reference signal when CLK and CLK go to a logic LOW state, enters the power-down mode, and later return to active operation. CLK and CLK may be left floating after they have been driven LOW for one complete clock cycle.

Symbol	Description	Test Conditions	Min.	Typ. ⁽²⁾	Max.	Unit
tPLH ⁽²⁾	LOW to HIGH Level Propagation Delay Time	AVDD = GND, OE = H, OS = L,		TBD		ns
		CLK to any output				
tPHL ⁽²⁾	HIGH to LOW Level Propagation Delay Time	AVDD = GND, OE = H, OS = L,		TBD		ns
		CLK to any output				
tjit(cc+)	Jitter (cycle-to-cycle)	166/200/266MHz	0		40	ps
tjit(cc-)			0		-40	1
tjit(per) ⁽³⁾	Jitter (period)	166/200/266MHz	-40		40	ps
tjit(hper) ⁽³⁾	Half-Period Jitter	166/200/266MHz	-60		60	ps
tslr(0) ^(1,4)	Output Clock Slew Rate (single-ended)	166/200/266MHz (20% to 80%)	1.5	2.5	3	V/ns
tslr(1) ^(1,4)	Output Enable (OE)		0.5			V/ns
	Input Clock Slew Rate		1	2.5	4	1
t(Ø) ⁽⁵⁾	Static Phase Offset	166/200/266MHz	-50		50	ps
t(Ø)DYN	Dynamic Phase Offset	166/200/266MHz	-50		50	ps
tsk(0)	Output Skew				40	ps
ten	Output Enable to any Y or \overline{Y}				8	ns
tDIS	Output Disable to any Y or \overline{Y}				8	ns
Vox ⁽⁶⁾	AC Differential Output Crosspoint Voltage	Differential outputs terminated with 120Ω	(Vdda/2)-0.1		(VDDQ/2)+0.1	V
VID(AC)	AC Differential Input Voltage		0.6		VDDQ+0.4	V
Vix	AC Differential Input Crosspoint Voltage		(Vdda/2)-0.15		(Vdda/2)+0.15	V
The PLL on th	e CSPU877A will meet all the above test parameters	while supporting SSC synthesizers with the fo	ollowing paramete	rs:		
SSC	Modulation Frequency		30		33	KHz
SSC	Clock Input Frequency Deviation		0		-0.5	%
f3dB	PLL Loop Bandwidth		2			MHz

AC ELECTRICAL CHARACTERISTICS⁽¹⁾

NOTES:

2. Refers to transition of non-inverting output.

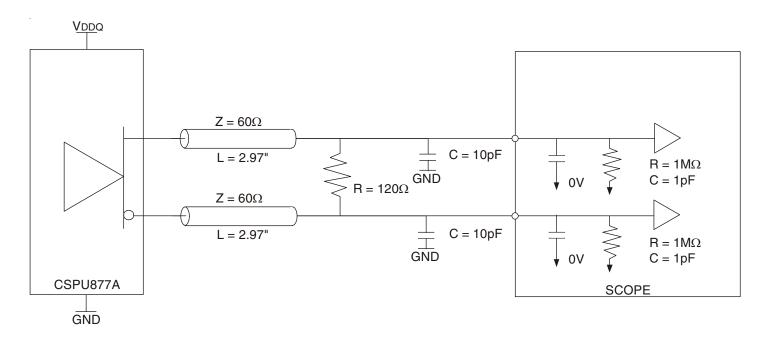
3. Period jitter and half-period jitter specifications are separate specifications that must be met independently of each other.

4. To eliminate the impact of input slew rates on static phase offset, the input slew rates of reference clock input (CLK, CLK) and feedback clock input (FBIN, FBIN) are recommended to be nearly equal. The 2.5V/ns slew rates are shown as a recommended target. Compliance with these nominal values is not mandatory if it can be adequately demonstrated that alternative characteristics meet the requirements of the registered DDR2 DIMM application.

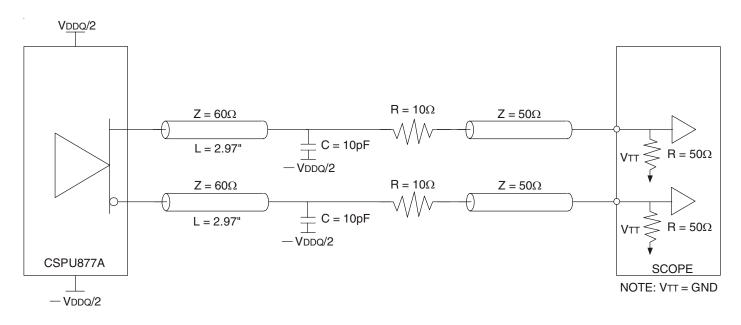
5. Static phase offset does not include jitter.

6. Vox is specified at the DDR DRAM clock input or test load.

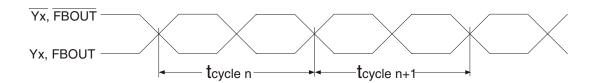
There are two different terminations that are used with the above AC tests. The output load shown in figure 1 is used to measure the input and output differential pair cross-voltage only. The output load shown in figure 2 is used to measure all other tests, including input and output slew rates. For consistency, use 50Ω equal length cables with SMA connectors on the test board.





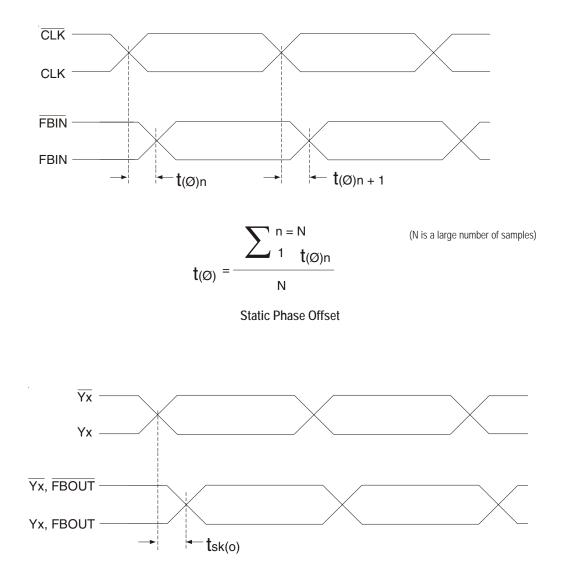




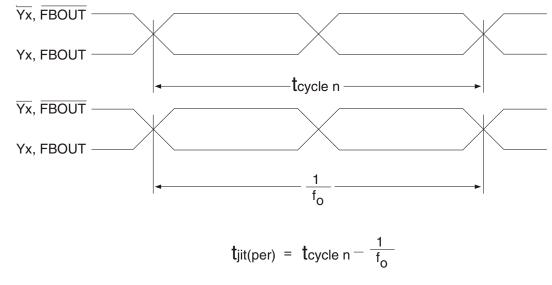


 $t_{jit(cc)} = t_{cycle n} - t_{cycle n+1}$

Cycle-to-Cycle jitter

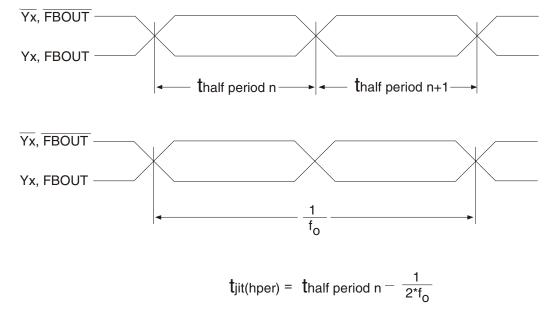


Output Skew



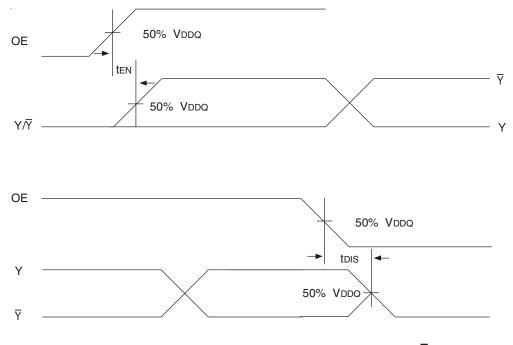
NOTE: fo = Average input frequency measured at CLK / $\overline{\text{CLK}}$

Period jitter

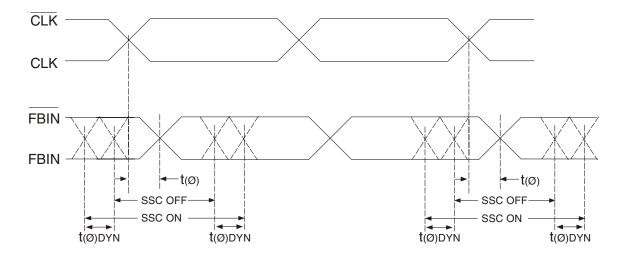


NOTE: fo = Average input frequency measured at CLK / $\overline{\text{CLK}}$

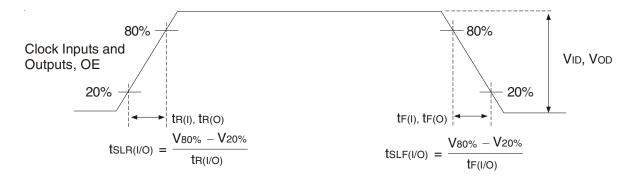
Half-Period jitter

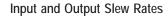


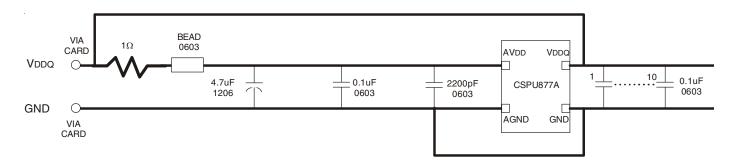
Time Delay Between Output Enable (OE) and Clock Output (Y, \overline{Y})



Dynamic Phase Offset







NOTES:

Place all decoupling capacitors as close to the CSPU877A pins as possible.

Use wide traces for AvDD and AGND.

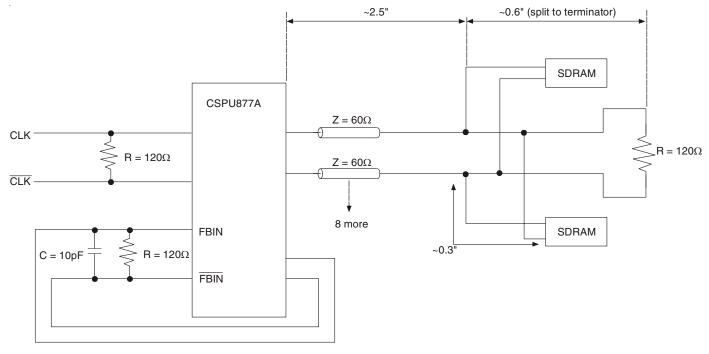
Recommended bead: Fair-rite P/N 2506036017Y0 or equivalent (0.8 Ω DC max., 600 Ω at 100MHz).

Recommended Filtering for the Analog and Digital Power Supplies (AVDD and VDDD)

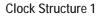
APPLICATION INFORMATION

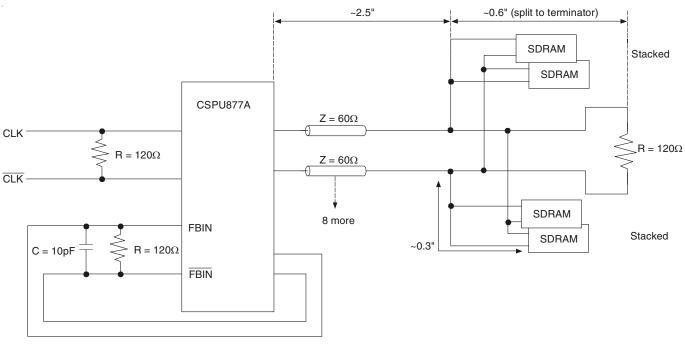
		Clock Loading on the PLL outputs (pF)			
Clock Structure	# of SDRAM Loads per Clock	Min.	Max.		
#1	2	3	5		
#2	4	6	10		

APPLICATION INFORMATION



Feedback path

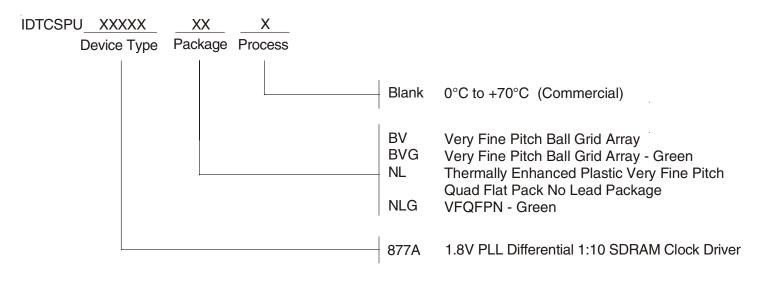




Feedback path

Clock Structure 2

ORDERING INFORMATION





CORPORATE HEADQUARTERS 6024 Silver Creek Valley Road San Jose, CA 95138 *for SALES:* 800-345-7015 or 408-284-8200 fax: 408-284-2775 www.idt.com *for Tech Support:* logichelp@idt.com